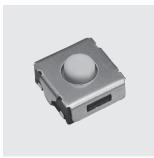
SMT3/SMTE3

Surface Mount Tactile Switches

Washable



RoHS Compliant

Features -

- **1. Compatible With Lead-Free, Reflow Soldering** Heat-resistance resin for lead-free soldering.
- 2. Washable (SMTE3 Series)
- 3. J-Lead Terminal Pins For High-Density Mounting
- 4. Anti-Static Electricity (SMTE3 Series) Ground terminal is provided to prevent damage to element caused by static electricity.

■ Specifications

	Max.	0.6VA max. (24VDC max. 30mA max.)	
Rating	Min.	Silver plated contacts	1mA 5VDC
		Gold plated contacts	10μA 5VDC
Initial contact resistance		100mΩ max. (1.5	imA 200μVAC)
Dielectric strength		250VAC 1 minute	
Insulation resistance		100MΩ min.	(100VDC)
Electrostatic capacity		5pF max.	
Electrical life		100,000 operations	
Stroke	SMT3	0.25mm	
	SMTE3	0.5mm	
Operating force	SMT3	1.18±0.39 N	
	SMTE3	1.96±0.98 N	
Operating temperature range		-25~+70°C	
Storage temperature range		-40~+85°C	





G 3 - 01 E - Z

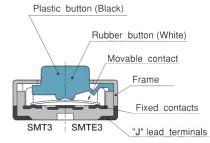
Series code Structure Contact plating Series No. Registration No. Packaging specs.

None	Standard type (Plastic button)	
Е	Immersion washable (Rubber button)	

None	Silver plated
G Gold plated	



■ Structure -



■ Table of Part Numbers -

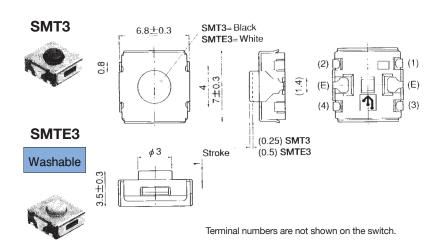
Structure	Packaging specifications	
Structure	Stick	Emboss taping
Standard type	SMT3-01-Z	SMT3-01E-Z ★SMTG3-01E-Z
Immersion washable	SMTE3-01-Z ★SMTEG3-01-Z	SMTE3-01E-Z ★SMTEG3-01E-Z

■Pad Layouts -

(Top view)

		(Top view)
Ground terminals	Without	With
Part No.	SMT3 · SMTE3 SMTG3 · SMTEG3	SMTE3 SMTEG3
Pattern dimensions	3.2 3.6 3.2 (2)	3.2 3.6 3.2 (1) (2) (E) (E) (4)

SPST



	Switchng function	
Part No.	_	↓ Push
SMT3-01-Z SMT3-01E-Z SMTG3-01E-Z SMTE3-01-Z SMTE3-01E-Z SMTEG3-01-Z SMTEG3-01E-Z	OFF	(ON)
Connecting terminals		$\frac{1}{2} - \frac{3}{4}$
Circuit diagrams	(1) O (2) (3) O (4) (E) O (E)	

(ON): Momentary

(E): GGround terminal (SMTE3 and SMTEG3 series)

■Soldering Specifications

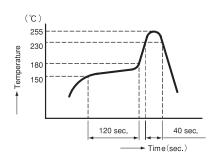
(1)Manual Soldering

Device : Soldering iron

 1350° C $\pm 10^{\circ}$ C; 3 ± 0.5 seconds

(2)Reflow Soldering

Device: Inline or batch system



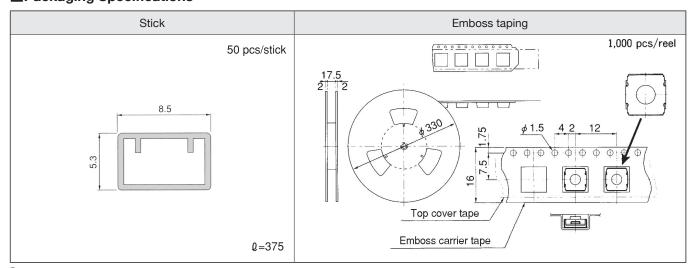
· Apply reflow soldering up to 2 times max.

Flux Cleaning

Since the **SMT3** series is not process sealed, be sure to use low-residue flux.

- (1) Solvent: Fluorine or Alcohol type
 - Cleaning with other solvents or water is not possible.
- (2) Cleaning after soldering should be done after the terminal temperature falls to 90°C or below, or after leaving the switch for five minutes or longer at room temperature. Cleaning temperature: 43°C, max.
- (3) Do not use ultrasonic cleaning.

■Packaging Specifications



When ordering, tape packaged version shall be supplied by request. Minimum packaging quantity for reel packaging is 1,000pcs per reel.